



# N-channel 600 V, 0.168 Ω typ., 18 A MDmesh™ M2 Power MOSFET in a TO-220FP ultra narrow leads package

Datasheet - production data

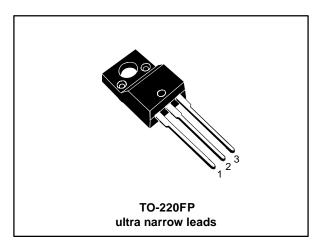
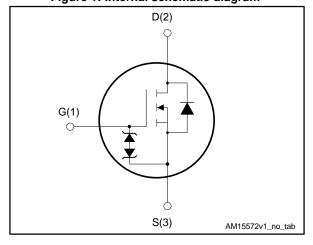


Figure 1: Internal schematic diagram



#### **Features**

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max	ID
STFU24N60M2	600 V	0.19 Ω	18 A

- Extremely low gate charge
- Lower R<sub>DS(on)</sub> x area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

### **Applications**

- Switching applications
- LLC converters, resonant converters

### **Description**

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

**Table 1: Device summary** 

Order code	Marking	Package	Packing
STFU24N60M2	24N60M2	TO-220FP ultra narrow leads	Tube

Contents STFU24N60M2

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STFU24N60M2 Electrical ratings

# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>G</sub> s	Gate-source voltage	± 25	V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	18 <sup>(1)</sup>	Α
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	12 <sup>(1)</sup>	Α
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	72 <sup>(1)</sup>	Α
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	30	W
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; $T_C$ = 25 °C)	2500	V
dv/dt (3)	Peak diode recovery voltage slope	Peak diode recovery voltage slope 15	
dv/dt (4)	MOSFET dv/dt ruggedness	50	V/ns
T <sub>stg</sub>	Storage temperature	- 55 to	°C
Tj	Max. operating junction temperature	150	C

#### Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	4.2	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient max	62.5	C/VV

**Table 4: Avalanche characteristics** 

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not repetitive (pulse width limited by T <sub>jmax</sub> )	3.5	Α
Eas	Single pulse avalanche energy (starting $T_j = 25^{\circ}C$ , $I_D = I_{AR}$ ; $V_{DD} = 50 \text{ V}$ )	180	mJ

<sup>&</sup>lt;sup>(1)</sup>Limited by maximum junction temperature.

<sup>&</sup>lt;sup>(2)</sup>Pulse width limited by safe operating area.

 $<sup>^{(3)}</sup>I_{SD} \leq$  18 A, di/dt  $\leq$  400 A/µs; VDSpeak < V(BR)DSS, VDD = 400 V.

 $<sup>^{(4)}</sup>V_{DS} \le 480 \text{ V}.$ 

Electrical characteristics STFU24N60M2

### 2 Electrical characteristics

(T<sub>C</sub> = 25 °C unless otherwise specified)

Table 5: On /off states

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	600			V
1	Zero gate voltage	V <sub>DS</sub> = 600 V			1	μΑ
IDSS	drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = 600 V, T <sub>C</sub> = 125 °C			100	μΑ
I <sub>GSS</sub>	Gate-body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 25 V			±10	μΑ
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	2	3	4	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9 A		0.168	0.19	Ω

Table 6: Dynamic

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
Ciss	Input capacitance		-	1060	1	pF
Coss	Output capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz},$	-	55	ı	pF
Crss	Reverse transfer capacitance	Ves = 0 V	-	2.2	-	pF
Coss eq. (1)	Equivalent output capacitance	V <sub>DS</sub> = 0 to 480 V, V <sub>GS</sub> = 0 V	-	258	-	pF
Rg	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0$	-	7	-	Ω
$Q_g$	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 18 \text{ A},$	-	29	ı	nC
Qgs	Gate-source charge	V <sub>GS</sub> = 10 V ( see Figure 15: "Test circuit for gate charge	-	6	-	nC
Q <sub>gd</sub>	Gate-drain charge	behavior")	-	12	-	nC

#### Notes:

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 9 \text{ A},$	ı	14	ı	ns
t <sub>r</sub>	Rise time	$R_G = 4.7 \Omega$ , $V_{GS} = 10 V$ (see Figure 14: "Test circuit for	-	9	-	ns
t <sub>d(off)</sub>	Turn-off delay time	resistive load switching times" and Figure 19: "Switching time waveform")	-	60	-	ns
t <sub>f</sub>	Fall time		ı	15	1	ns

 $<sup>^{(1)}</sup>C_{oss\ eq.}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

Table 8: Source drain diode

Symbol	Parameter	Parameter Test conditions		Тур.	Max.	Unit
I <sub>SD</sub> <sup>(1)</sup>	Source-drain current		-		18	Α
I <sub>SDM</sub> <sup>(1)(2)</sup>	Source-drain current (pulsed)		-		72	Α
V <sub>SD</sub> <sup>(3)</sup>	Forward on voltage	I <sub>SD</sub> = 18 A, V <sub>GS</sub> = 0 V	-		1.6	V
t <sub>rr</sub>	Reverse recovery time	$I_{SD} = 18 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s,}$	-	332		ns
Qrr	Reverse recovery charge	V <sub>DD</sub> = 60 V ( see Figure 16: "Test circuit for inductive load	-	4		μC
I <sub>RRM</sub>	Reverse recovery current	switching and diode recovery times")	-	24		Α
t <sub>rr</sub>	Reverse recovery time	$I_{SD} = 18 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	450		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ °C}, (see Figure 16: "Test circuit for$	-	5.5		μC
I <sub>RRM</sub>	Reverse recovery current	inductive load switching and diode recovery times")	-	25		А

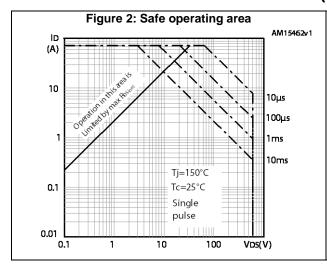
#### Notes:

 $<sup>\</sup>ensuremath{^{(1)}}\xspace$  The value is rated according to  $R_{thj\text{-case}}$  and limited by package.

 $<sup>^{(2)}</sup>$ Pulse width limited by safe operating area.

 $<sup>^{(3)}</sup>$ Pulsed: pulse duration = 300  $\mu$ s, duty cycle 1.5%.

# 2.1 Electrical characteristics (curves)



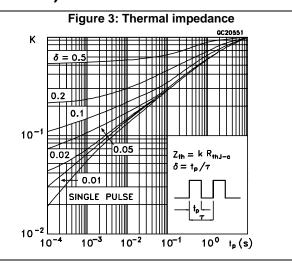
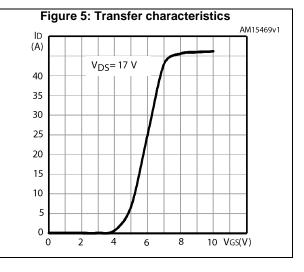
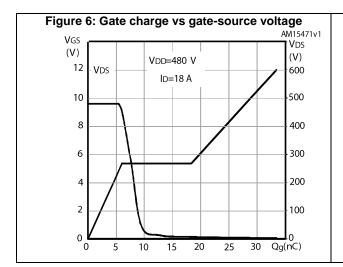
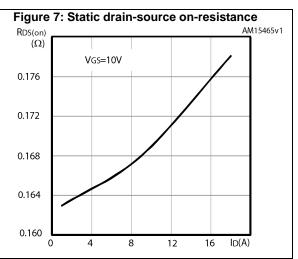


Figure 4: Output characteristics AM15470v1 V<sub>GS</sub>= 8, 9, 10 V (A)  $V_{GS} = 7V$ 40 35 30 25 V<sub>GS</sub>= 6V 20 15 10 V<sub>GS</sub>= 5 V 5 V<sub>GS</sub>= 4V 0 5 10 15 20 VDS(V)







STFU24N60M2 Electrical characteristics

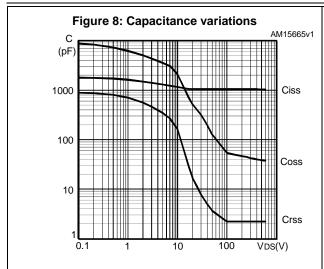


Figure 9: Normalized gate threshold voltage vs. temperature Eoss (JJ) 8 7 6 4 3 2 300 400 500 600 100 200  $V_{DS}(V)$ 

Figure 10: Normalized on-resistance vs temperature

VGS(th)
(norm)

1.1

1.0

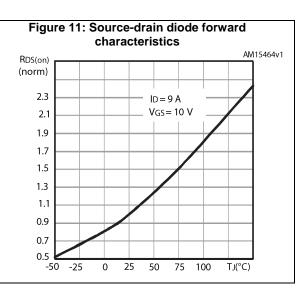
0.9

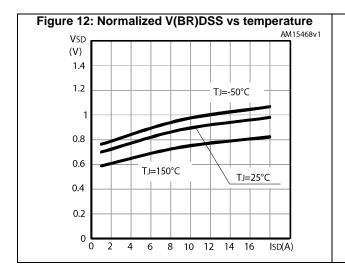
0.8

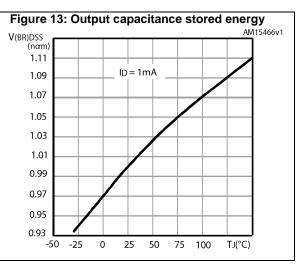
0.7

0.6

-50 -25 0 25 50 75 100 TJ(°C)







Test circuit STFU24N60M2

### 3 Test circuit

Figure 14: Test circuit for resistive load switching times

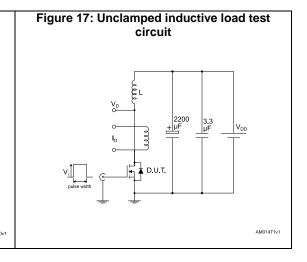
Figure 15: Test circuit for gate charge behavior

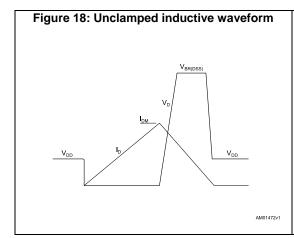
12 V 47 KQ 100 nF D.U.T.

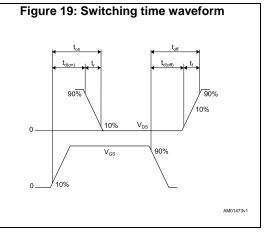
VGS 1 KQ 100 NF D.U.T.

AM01469v1

Figure 16: Test circuit for inductive load switching and diode recovery times







# 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

### 4.1 TO-220FP package information

F1(x3)D G1 Ε 8576148\_1

Figure 20: TO-220FP ultra narrow leads package outline

Table 9: TO-220FP ultra narrow leads mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.40		4.60
В	2.50		2.70
D	2.50		2.75
Е	0.45		0.60
F	0.65		0.75
F1	-		0.90
G	4.95		5.20
G1	2.40	2.54	2.70
Н	10.00		10.40
L2	15.10		15.90
L3	28.50		30.50
L4	10.20		11.00
L5	2.50		3.10
L6	15.60		16.40
L7	9.00		9.30
L8	3.20		3.60
L9	-		1.30
Dia.	3.00		3.20

STFU24N60M2 Revision history

# 5 Revision history

Table 10: Document revision history

Date	Revision	Changes	
12-Mar-2015	1	Initial release	
08-Sepr-2015	2	Datasheet status promoted from preliminary to production data	

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